



finetech

Media Contact:

Jody Mahaffey
e-Reach Communications
480-216-5049
jody@ereach.co

Finetech's New Sigma Bonder 0.5µm Accuracy for Large Die on Wafer Level Substrates and High Force Applications

Gilbert, AZ - July 8, 2015 - [Finetech](#) introduces the new [FINEPLACER® Sigma bonder](#), designed to provide a solution for large die up to 100mm, combined with a working area of 450 x 300 mm. The FINEPLACER® Sigma is ideally suited for high-density array applications and high bond force (up to 1000N) requirements, coupled with Finetech's renowned sub-micron placement accuracy.

The system is the ideal choice for a wide variety of Wafer Level Packaging (FOWLP, W2W, C2W) with high bump count used to assemble MEMS/MOEMS, IR/ image sensors, focal plane arrays, and high power device packaging. This includes assembly of complex 2.5D and 3D IC packages that require high accuracy across the entire surface of large substrates. The FINEPLACER® Sigma can also pick up from and bond to 300mm wafers.

The cornerstone element of the new bonder is FPXvision™, the newest generation of Finetech's Vision Alignment Systems (VAS). The FPXvision™ provides the highest resolution at all magnification levels and real-time optimized camera images. It enables the smallest devices and features to be clearly observed across the entire field of view, even with large components and substrates. Touch screen magnifiers allow zoomed images anywhere in the field of view. Two high definition cameras and specially developed optics ensure that the cameras' full resolution potential is tapped. FPXvision™ is the first vision system to introduce pattern recognition to a semi-automated die bonding platform.



The FINEPLACER® Sigma allows endless fields of application to users working with medical technologies, R&D, mil/aero, semiconductor, and automotive industries. The optimal process environment can be configured for each type of application, including the latest technologies such as vacuum bonding, sintering or metal diffusion (Cu/Cu).

Neil O'Brien, General Manager of Finetech USA, states, "It is very exciting to offer such a flexible bonding platform to address the needs of large or small die, with high density I/O bonded to virtually any size substrate. We have always been known for our sub-micron technology, but to offer this in a semi-automated system that can handle 300mm wafers and apply forces up to 1000N is incredible. Our new FPXvision™ technology with pattern recognition and alignment verification, will

help increase yields for today's most demanding applications."

[Click here](#) to view the full press release on our website.

About Finetech

Finetech manufactures innovative, high-accuracy equipment for leading-edge bonding, micro assembly and rework challenges. The FINEPLACER® systems range from manual systems for R&D and prototype environments to automated models for high-mix or higher volume production and are designed to be modular for maximum process flexibility. The company services customers in a broad range of industries including aerospace, medical technology, consumer electronics, semiconductor, optoelectronics, military, universities and research. With installations worldwide, Finetech works with start-up groups and large multi-national corporations alike to provide solutions to all of today's most challenging devices

To learn more about Finetech please visit www.finetechusa.com.

Company Contact:
Adrienne Gerard
Finetech USA
Tel: +1 480-893-1630
Email: adg@finetechusa.com